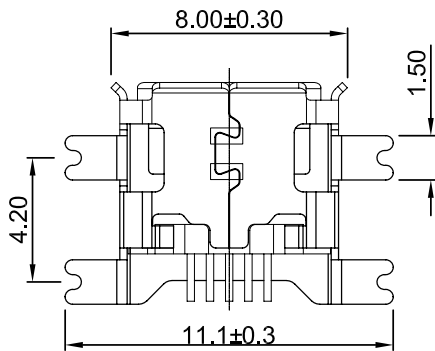
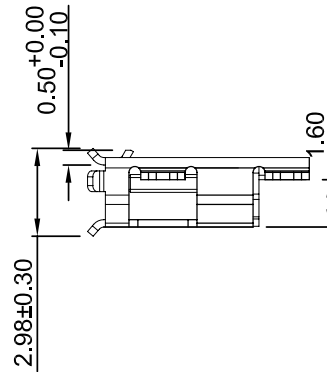
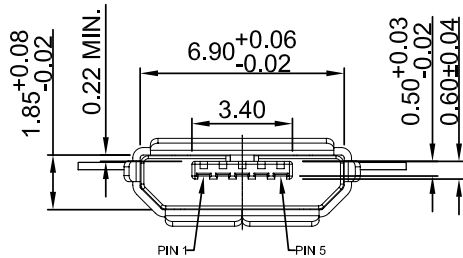
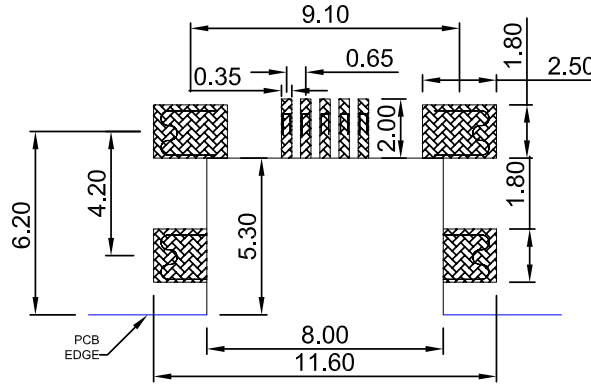
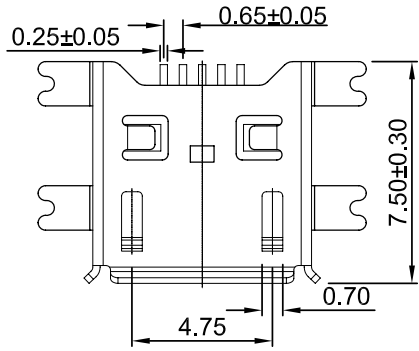


P.C. Board SMD Layout



Specifications

- Contact Current Rating: 2.1A Min.
- Voltage Rating: 30V AC rms.
- Contact Resistance: 30mΩ Max.
- Dielectric Withstanding: Unmated Contact 100V AC rms.
60MHz for 1 Minute
- Insulation Resistance: 1000MΩ Min. 100V DC
- Temperature Range: -20°C to 85°C
- Insertion Force: 35N Max.
- Withdrawal Force: 8N Min.
- Durability: 10,000 cycles.
- Housing: Thermoplastic High-Temp. UL94V-0 LCP, Black
- Contact: C2680-H T=0.2
- Shell: C2680-H T=0.25
- Contact Plating: 50μ"~80μ" Ni/G.F Plated Over All
- Shell Plating: 50μ"~80μ" Min. Matte Tin Plated Over All

Part Numbering System

ULCR - 05 B 1 - F X X X

- Series** _____
- No. of Pins** _____
05
- Type Option:** _____
B = B Type
- Style:** _____
1 = Offset PCB 1.6mm
- Contact Option:** _____
F = Female
- Contact Plated:** _____
- Film Option:** _____
Nil = No Film
F = Film
- Packing Method:** _____
T = Tape & Reel

* Contact Plating Option	Full Gold Plating	Gold Plated On Contact Area Tin Plated on Solder Area	Full Tin Plating
		G : Gold Flash G10: Gold 10u" G15: Gold 15u" G30: Gold 30u"	S: Gold Flash S10: Gold 10u" S15:Gold 15u" S30: Gold 30u"

General Tolerance	
X. ± 0.50	X.° ± 5°
.X ± 0.20	.X° ± 2°
.XX ± 0.10	.XX° ± 1°
Units : mm	